



NOTES:

1. MATERIAL: BLACK 92% Al₂O₃
2. METALLIZATION: MINIMUM 80 MICROINCHES ELECTROLESS GOLD OVER 50 TO 350 MICROINCHES ELECTROLESS NICKEL AND REFRACTORY METAL.
3. PARTS SUPPLIED TO CEPC STANDARD CHIP CARRIER SPECIFICATION.
4. DIE PAD CONNECTED TO INDEX CORNER.
5. DIE PAD, SEAL RING, AND BONDING PADS ARE ELECTRICALLY ISOLATED.

REVISIONS	C	REVISED B/C ON INDEX CORNER	06-08-92	CLJ	920405
	B	REVISED DIMENSIONS & TO ELECTROLESS	12-12-91	LJW	911238
	A		12-2-86	LJ	GPC
	ISSUE	CHANGE RECORD	DATE:	DR.	CH.

Coors Electronic Package Company

Chattanooga, TN 37406-0327

INCHES [mm]

TOLERANCES Unless Otherwise Specified

+/- 1X

Not Less Than +/- 0.005 [0.127]

TITLE:	16 LEAD CHIP CARRIER
PART No:	SU-88216-ZC
DWG No:	78-8044-3236-0

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